

EADS Astrium

Procedure

Herschel

Title: **Herschel EQM SVM Simulator Integration**CI-No: *152000*Prepared by: P. Mack *P. Mack* Date: 20.05.05Checked by: C. Schlosser *C. Schlosser* 23.05.05Product Assurance: *for* R. Stritter *R. Stritter* 31.05.05Configuration Control: W. Wietbrock *W. Wietbrock* 31.05.05Project Management: W. Ruhe *W. Ruhe* 31.5.05

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Issue	Date	Sheet	Description of Change	Release
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Table of Content

1	Introduction	6
1.1	Scope	6
2	Documents	7
2.1	Applicable Documents (AD)	7
2.2	Reference Documents	7
3	Configuration	8
3.1	Initial EQM SVM-simulator/H/W configuration	8
3.2	Environmental Requirements	8
3.3	Herschel SVM Simulator Axis orientation	9
4	Requirements	10
4.1	General Instructions for SVM Simulator Integration	10
4.1.1	Safety Requirements, Precautions	10
4.1.2	QA Requirements	10
4.1.3	Prerequisites	10
4.1.4	ESD Constraints	11
4.2	Personnel	11
5	Ground Support Equipment GSE	12
5.1	Facility Equipment/Instrumentation (clean room cl. 100 000)	12
5.2	Special Equipment	12
6	Documentation Requirements	13
6.1	Changes of Procedure during integration	13
6.2	Non-Conformance Reports	14
6.3	Test Report	14
7	Activity Flow	15
7	Activity flow (cont'd)	16
8	Step-by-Step Procedure	17

8.1	Mechanical Integration of HIFI Warm Units (WU's)	17
8.2	Grounding of HIFI WU's	19
8.3	Installation of HIFI Warm Units Interconnecting Harness	20
8.4	HIFI WU's Bench Test	21
8.5	Mechanical Integration of PACS Warm Units (WU's)	22
8.6	Grounding of PACS Warm Units (WU's)	24
8.7	Installation of PACS Warm Units Interconnecting Harness	25
8.8	PACS WU's Bench Test	26
8.9	Mechanical Integration of SPIRE Warm Units (WU's)	27
8.10	Grounding of SPIRE Warm Units (WU's)	29
8.11	Installation of SPIRE Warm Units Interconnecting Harness	30
8.12	SPIRE WU's Bench Test	31
8.13	Integration of SIH Support Brackets to SVM Simulator Closure Panels	32
8.14	Installation of SVM HIFI SIH from SVM Harness Brackets to HIFI Warm Units I/F's	33
8.15	Installation of External PACS SIH from SVM Brackets to PACS Warm Units I/F's	34
8.16	Installation of External SPIRE SIH from SVM Brackets to SPIRE Warm Units I/F's	35
8.17	Instrument WU's Bus and Power cabling integration on SVM lower panels for HIFI, PACS and SPIRE	36
8.18	Instrument WU's electrical integration Procedure with IDAS	37

Table of Figures

Fig.: 1 SVM Simulator Coordinates system, vertical axis equal X-axis..... 9

Fig.: 2 principal SVM simulator integration flow..... 16

1 Introduction

1.1 Scope

This Procedure describes all activities for instrument Warm Units (WU's) integration to the EQM SVM simulator.

The document is built up as a step by step procedure and starts with the mechanical integration of warm units (WU's) to the SVM simulator side panels and will be completed with instruments SVM power and bus cabling integration and verification.

For autonomous activity blocks (e. g. SIH integration, functional testing of WU's) separate specific procedures are available and this present procedure shall have the character of a leading procedure.

2 Documents

2.1 Applicable Documents (AD)

Applicable documents (AD) are defined as being documents which are needed to complete the work, they are considered as being integral part of this document, as far as specifically called-up.

The following documents in their latest issue are applicable to the specification :

AD #	Document Title	Document Identifier
AD 01	SVM simulator drawing set	2547-152-000-500-01-0A
AD 02	HIFI warm unit handling procedure	SRON-U/WIH/PR/2004-001
AD 03	PACS warm units handling procedure	PACS-ME-HP-001
AD 04	SPIRE warm units handling procedure	SPIRE-RAL-PRC-002181
AD 05	HIFI stand alone test procedure	SRON-U/HIFI/PR/2004-007
AD 06	PACS stand alone test procedures	PACS-ME-TP-0016
AD 07	SPIRE stand alone test procedure	SPIRE-RAL-PRC-002422
AD 08	HIFI WU electrical integration Procedure with IDAS	HP-2-ASED-TP-0058
AD 09	PACS WU electrical integration Procedure with IDAS	HP-2-ASED-TP-0055
AD 10	SPIRE WU electrical integration Procedure with IDAS	HP-2-ASED-TP-0057
AD 11	HIFI 1	HP-NXH-DW-1024
AD 12	HIFI 2	HP-NXH-DW-1023
AD 13	PACS	HP-NXH-DW-1021
AD 14	SPIRE	HP-NXH-DW-1022
AD 15		H-P-2-ASPI-SP-0902

2.2 Reference Documents

RD 01	PA Plan	HP-2-ASED-PL-0007
RD 02	General Design and Interface Requirements (GDIR)	H-P-1-ASPI-SP-0027
RD 03	Reinigungsvorschrift für Komponenten im Projekt Herschel	HP-2-ASED-PR-0008
RD 04	Herschel PLM/EQM General AIT Procedure	HP-ASED-PR-0012
RD 05	EQM AIT Plan	HP-ASED-PL-0022
RD 06	List of Acronyms	HP-2-ASPI-LI-0077

3 Configuration

3.1 Initial EQM SVM-simulator/H/W configuration

- SVM simulator mounted and placed in clean room class 100 000
- All vertical side panels and horizontal closure panels drilled according warm units -and harness support brackets I/F hole pattern

3.2 Environmental Requirements

All activities according this procedure have to be performed in a **clean room class 100 000** Federal standard 209 E

Temperature: 22 °C ± 3 °C

Relative Humidity: 40% to 60%

3.3 Herschel SVM Simulator Axis orientation

For all axis definitions according this procedure the Herschel coordinate System is applicable.

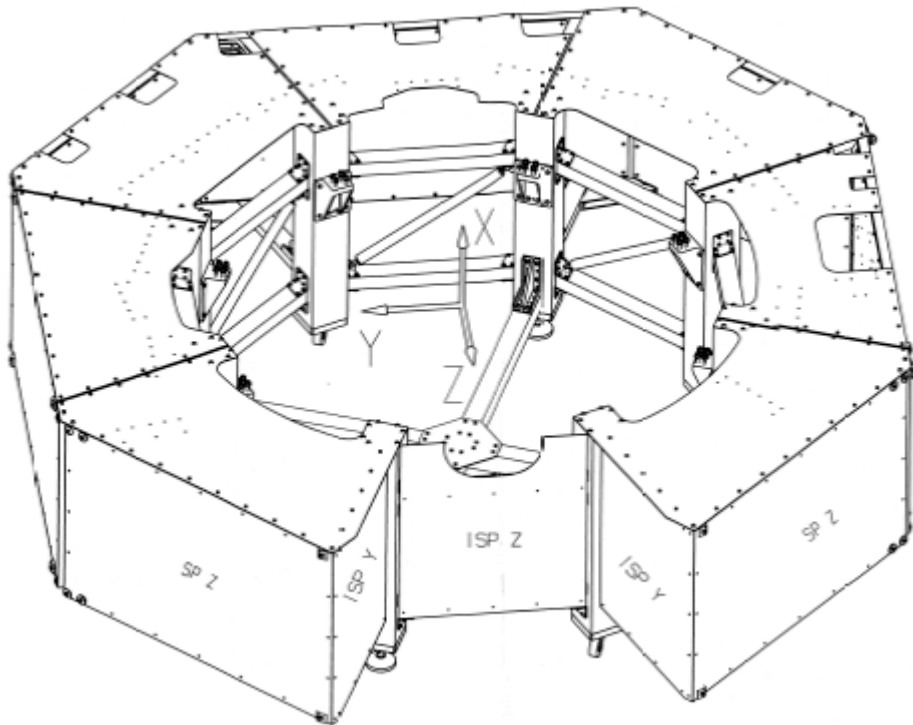
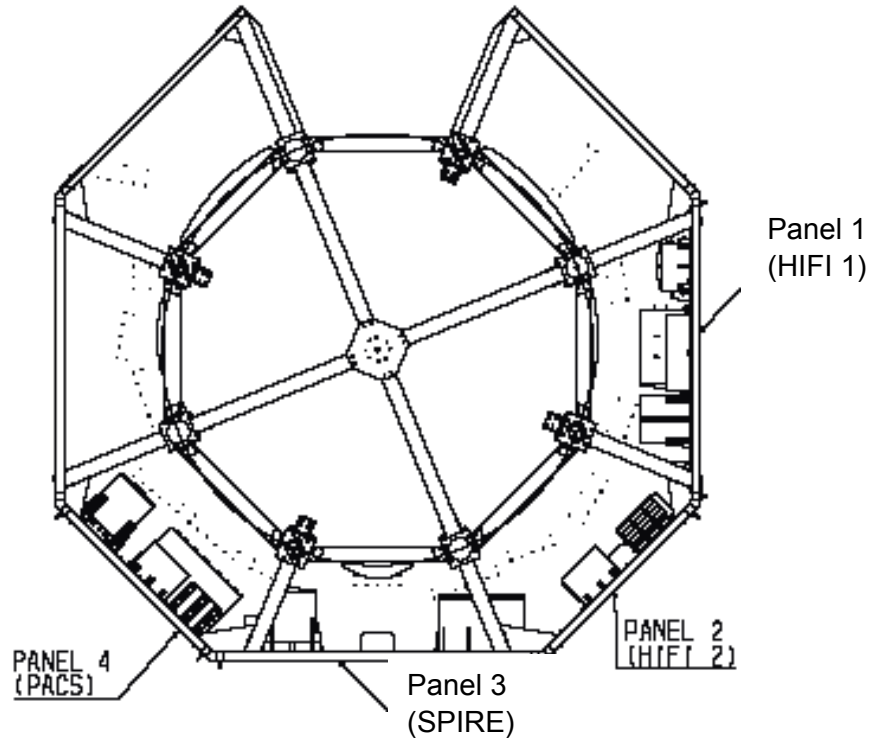


Fig.: 1 SVM Simulator Coordinates system, vertical axis equal X-axis

4 Requirements

4.1 General Instructions for SVM Simulator Integration

4.1.1 Safety Requirements, Precautions

No special hazards are expected. Respect of the standard technical rules for mechanical and electrical integration and test activities are sufficient. ESD safety precautions to be respected if requested.

4.1.2 QA Requirements

Quality Assurance shall monitor all operations (handling, transportation, dismantling and installation) as necessary to assure compliance with this procedure and the applicable requirements of the PA-Plan AD 01.

In the course of this procedure QA shall pay a particular attention to

- the application of adequate protections to critical surfaces
- the records in the log-sheet
- the recording of the serial number of the test equipment used
- to ensure that the test equipment used is within actual calibration cycle

QA has to make sure that NCR's are raised when applicable and treated by NRB procedure as defined in the PA-Plan AD 01.

After the conclusion that a activity is successfully completed this activity has to be signed by the responsible AIT- and QA engineer in the step by step procedure. Also relevant log sheets have to be filled out and signed

4.1.3 Prerequisites

At least the following tasks have to be successfully completed before start with PLM SVM Simulator Integration:

- Formal release to start activities given by QA available
- This procedure released and accepted

All parts and tools required available and operational

4.1.4 ESD Constraints

In order to prevent ESD sensitive H/W from any possible damages by accidental electrostatic discharges an ESD protected area must be defined and setup during ESD sensitive activities:

- Floor and test bench of the ESD protected area has to be covered with anti-static mats
- During all handling activities (as transport, mounting, mating/de-mating of connectors, measurements with individual measurement devices, etc.) the operator has to work on anti static mats with correct clothing and personal grounding-straps
- Adequate ESD clothing is required:
 - Anti static coat
 - Anti static gloves
 - Anti static boots
- Transportation of ESD sensitive H/W will be made only in ESD protective bag or box

4.2 Personnel

Personnel necessary to complete activities according this present procedure

Title	Function	Name
Test conductor	Overall responsible	*)
Mechanical Operator	Mechanical operations	*)
Electrical operator	Competent for routing/fixation of harness, verification of harness function	*)
QA Representative	To ensure QA requirements	*)

*) Names to be registered prior to start of test activities

5 Ground Support Equipment GSE

GSE necessary for this procedure

5.1 Facility Equipment/Instrumentation (clean room cl. 100 000)

Equipment	Reference
Facility crane and standard hoisting accessories	-
Set of standard integration tooling	-
Standard cleaning equipment (such as IPA, lintfree rags, ultrasonic bath, UV lamp, halogen lamp, vacuum cleaner...)	-

5.2 Special Equipment

Equipment	Reference
GOSSEN METRAWATT bonding measurement device	Metra Hit 271
HIFI provided EGSE and test equipment	tbd
PACS provided EGSE and test equipment	tbd
SPIRE provided EGSE and test equipment	tbd

6 Documentation Requirements

6.1 Changes of Procedure during integration

Any activity deviating from the approved procedure requires the agreement of Project, AIV, QA responsible (Alcatel and ESA), and shall be documented via procedure variation sheet and listed in the table below:

No.	Para.	Variation Description	Signature				Action req.
			TC	PA	ASPI	ESA	

6.2 Non-Conformance Reports

Any failure or anomaly be found during work according this procedure a Non-conformance report shall be written. For major NCR's test shall be continued only upon written or verbal authorisation of Customer (Alcatel and ESA).

All Non - Conformances generated during this test shall be recorded in the table below:

NCR - No.	NCR - Title	Date	Status

6.3 Test Report

The test report shall cover the following contents:

- Summary (specimen, procedure)
- Activity sequences (dates of actual sequence)
- Appendix A: filled out test procedure
- Appendix B: list of NCR's/NRB's

7 Activity Flow

7.1 Mechanical Integration of HIFI WU's

7.2 Grounding of HIFI WU's

7.3 Installation of HIFI WU's interconnecting harness

7.4 HIFI WU's bench test (stand alone test)
(not part of this procedure)

7.5 Mechanical Integration of PACS warm units

7.6 Grounding of PACS WU's

7.7 Installation of PACS WU's interconnecting harness

7.8 PACS WU's bench test (stand alone test)
(not part of this procedure)

7.9 Mechanical Integration of SPIRE WU's

7.10 Grounding of SPIRE WU's

7.11 Installation of SPIRE WU's interconnecting harness

7.12 SPIRE WU's bench test (stand alone test)
(not part of this procedure)

7.13 Integration of SIH support brackets to SVM closure panels

7 Activity flow (cont'd)

- | | |
|-------------|---|
| 7.14 | Installation of SVM HIFI SIH from SVM harness brackets to HIFI warm units I/F's (not part of this procedure) |
| 7.15 | Installation of SVM PACS SIH from SVM harness brackets to PACS warm units I/F's (not part of this procedure) |
| 7.16 | Installation of SVM SPIRE SIH from SVM harness brackets to SPIRE warm units I/F's (not part of this procedure) |
| 7.17 | SVM EGSE cable I/F bracket and EGSE cabling integration on lower panels for HIFI, PACS and SPIRE |
| 7.18 | Instrument WU's electrical integration Procedure with IDAS (not part of this procedure) |

Fig.: 2 principal SVM simulator integration flow

(Sequence of tasks can vary, parallel activities accepted if feasible)

8 Step-by-Step Procedure

8.1 Mechanical Integration of HIFI Warm Units (WU's)

Step	Activity	Nominal Value	Actual Value	Remarks
8.1.1.1	Perform incoming inspection of HIFI WU's incl. HIFI WU's interconnecting harness: <ul style="list-style-type: none"> • cleaning and cleanliness inspection of ext. surfaces • visual inspection • completeness of documentation (ADP) 			
8.1.1.2	Remove side panel 1 (-Y axis) and side panel 2 (-Y, -Z) from SVM simulator structure and place panels on adequate support to allow comfortable access for WU's integration. (Lower panels remains installed)			
8.1.1.3	Ensure acceptable grounding of side panels before WU's integration			
8.1.1.4	Preinstall the following HIFI WU's on side panel 1: <ul style="list-style-type: none"> • LCU • LSU Simulator • HRH • WOH • WEH • IFH (Connector bracket) and on side panel 2: <ul style="list-style-type: none"> • FCU • ICU All screws hand tight			ESD precautions to be respected

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

Step	Activity	Nominal Value	Actual Value	Remarks
8.1.1.5	Adapt grounding straps from each HIFI WU to side panel and copy grounding strap I/F hole on side panels			ESD precautions to be respected
8.1.1.6	Perform drilling of marked grounding strap I/F holes in side panel 1 and side panel 2. For drilling remove HIFI WU's from side panels. Use vacuum cleaner.			ESD precautions to be respected
8.1.1.7	Perform cleaning of side panel1 and side panel 2 with IPA and lint free rags			
8.1.1.8	Final mech. installation of HIFI WU's and equipment on side panel 1: <ul style="list-style-type: none"> • IFH (Connector bracket) • LCU • LSU Simulator • HRH • WOH • WEH and on side panel 2: <ul style="list-style-type: none"> • FCU • ICU Screw down of HIFI WU's fixation screws with defined torque Torque to be applied Marking of fixation screws after application of defined torque	M5 - 3.8 Nm ± 0.3 Nm M6 - 5.0 Nm ± 0.5 Nm		ESD precautions to be respected
8.1.1.9				

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

8.2 Grounding of HIFI WU's

Step	Activity	Nominal Value	Actual Value	Remarks
8.2.1.1	Installation of grounding straps from HIFI WU's to side panel 1: <ul style="list-style-type: none"> • LCU • LSU Simulator • HRH • WOH • WEH and to side panel 2: <ul style="list-style-type: none"> • FCU • ICU Screw down of HIFI grounding straps fixation screws with defined torque Torque to be applied Marking of fixation screws after application of defined torque	M5 - 3.8 Nm ± 0.3 Nm		ESD precautions to be respected
8.2.1.2	Perform grounding verification measurement between HIFI WU's housings and side panel 1 resp. side panel 2 Documentation of measured values of side panel 1: <ul style="list-style-type: none"> • LCU • LSU SIMULATOR • HRH • WOH • WEH and of side panel 2: <ul style="list-style-type: none"> • FCU • ICU Use bonding measurement device Metrawatt with Kelvin probes in four wire measurement technique and 1 amp measurement current	≤ 2.5 mOhm		ESD precautions to be respected

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

8.3 Installation of HIFI Warm Units Interconnecting Harness

Step	Activity	Nominal Value	Actual Value	Remarks
8.3.1.1	Pre-installation and definition of routing of HIFI WU's interconnecting harness on side panel 1 and side panel 2. Copy positions of cable tie anchors onto side panel 1 and side panel 2			
8.3.1.2	Fixation of cable tie anchors on side panel 1 and side panel 2 according marked positions of step before			
8.3.1.3	Final fixation of HIFI interconnecting harness on side panel 1 and side panel 2			
8.3.1.4	Make contact of HIFI warm units interconnecting harness with WU's. To be performed by HIFI instrument representative			ESD precautions to be respected

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

8.4 HIFI WU's Bench Test

Step	Activity	Nominal Value	Actual Value	Remarks
8.4.1.1	General Remark: HIFI stand alone test will be performed with instrument provided EGSE and procedure SRON-U/HIFI/PR/2004-007			Test can be performed with side panel away or side panel installed onto SVM simulator
8.4.1.2	If side panel 1 is not installed perform installation of side panel 1 onto SVM simulator. For movement use facility crane and standard hoisting slings. Screw down side panel 1 onto SVM simulator (-Y axis) <ul style="list-style-type: none"> application of defined torque. Torque to be applied 	M8 - 15 Nm ± 0.5 Nm		
8.4.1.3	If side panel 2 is not installed perform installation of side panel 2 onto SVM simulator. For movement use facility crane. Screw down side panel 2 onto SVM simulator (-Y, -Z) <ul style="list-style-type: none"> application of defined torque. Torque to be applied 	M8 - 15 Nm ± 0.5 Nm		

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

8.5 Mechanical Integration of PACS Warm Units (WU's)

Step	Activity	Nominal Value	Actual Value	Remarks
8.5.1.1	Perform incoming inspection of PACS WU's incl. PACS WU's interconnecting harness: <ul style="list-style-type: none"> • cleaning and cleanliness inspection of ext. surfaces • visual inspection • completeness of documentation (ADP) 			
8.5.1.2	Remove side panel 4 (Y, -Z) from SVM simulator structure and place panel on adequate support to allow comfortable access for WU's integration			
8.5.1.3	Ensure acceptable grounding of side panels before WU's integration			
8.5.1.4	Preinstall the following PACS WU's on side panel 4: <ul style="list-style-type: none"> • BOLC • DEC/MEC • DPU • SPU All screws hand tight			ESD precautions to be respected
8.5.1.5	Adapt grounding straps from each PACS WU to side panel 4 and copy grounding strap I/F hole on side panel			ESD precautions to be respected

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

Step	Activity	Nominal Value	Actual Value	Remarks
8.5.1.6	Perform drilling of marked grounding strap I/F holes in side panel 4. For drilling remove PACS WU's from side panel. Use vacuum cleaner.			ESD precautions to be respected
8.5.1.7	Perform cleaning of side panel 4 with IPA and lint free rags			
8.5.1.8	Final mech. installation of PACS WU's on side panel 4: <ul style="list-style-type: none"> • BOLC • DEC/MEC • DPU • SPU Screw down of PACS WU's fixation screws with defined torque Torque to be applied Marking of fixation screws after application of defined torque	M5 - 3.8 Nm ± 0.3 Nm M6 - 5.0 Nm ± 0.5 Nm		ESD precautions to be respected

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

8.6 Grounding of PACS Warm Units (WU's)

Step	Activity	Nominal Value	Actual Value	Remarks
8.6.1.1	Installation of grounding straps from PACS WU's to side panel 4: <ul style="list-style-type: none"> • BOLC • DEC/MEC • DPU • SPU Screw down of HIFI grounding straps fixation screws with defined torque Torque to be applied Marking of fixation screws after application of defined torque	M5 - 3.8 Nm ± 0.3 Nm		ESD precautions to be respected
8.6.1.2	Perform grounding verification measurement between PACS WU's housings and side panel 4 Documentation of measured values: <ul style="list-style-type: none"> • BOLC • DEC/MEC • DPU • SPU Use bonding measurement device Metrawatt with Kelvin probes in four wire measurement technique and 1 amp measurement current	≤ 2.5 mOhm		ESD precautions to be respected

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

8.7 Installation of PACS Warm Units Interconnecting Harness

Step	Activity	Nominal Value	Actual Value	Remarks
8.7.1.1	Pre-installation and definition of routing of PACS WU's interconnecting harness onto side panel 4 Copy positions of cable tie anchors onto side panel 4			
8.7.1.2	Fixation of cable tie anchors on side panel 4 according marked positions of step before			
8.7.1.3	Final fixation of PACS interconnecting harness on side panel 4			
8.7.1.4	Make contact of PACS warm units interconnecting harness with WU's. To be performed by PACS instrument representative			ESD precautions to be respected

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

8.8 PACS WU's Bench Test

Step	Activity	Nominal Value	Actual Value	Remarks
8.8.1.1	General Remark: PACS stand alone test will be performed with instrument provided EGSE and procedure PACS-ME-TP-0016			Test can be performed with side panel away or side panel installed onto SVM simulator
8.8.1.2	If side panel 4 is not installed perform installation of side panel 4 onto SVM simulator. For movement use facility crane and standard hoisting slings. Screw down side panel 4 onto SVM simulator (Y/ -Z xis) <ul style="list-style-type: none"> • application of defined torque. Torque to be applied 	M8 - 15 Nm ± 0.5 Nm		

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

8.9 Mechanical Integration of SPIRE Warm Units (WU's)

Step	Activity	Nominal Value	Actual Value	Remarks
8.9.1.1	Perform incoming inspection of SPIRE WU's incl. SPIRE WU's interconnecting harness: <ul style="list-style-type: none"> • cleaning and cleanliness inspection of ext. surfaces • visual inspection completeness of documentation (ADP)			
8.9.1.2	Remove side panel 3 (-Z) from SVM simulator structure and place panel on adequate support to allow comfortable access for WU's integration			
8.9.1.3	Ensure acceptable grounding of side panels before WU's integration			
8.9.1.4	Preinstall the following SPIRE WU's on side panel 3: <ul style="list-style-type: none"> • DCU • FCU • DPU All screws hand tight			ESD precautions to be respected
8.9.1.5	Adapt grounding straps from each SPIRE WU to side panel 3 and copy grounding strap I/F hole on side panel			ESD precautions to be respected

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

Step	Activity	Nominal Value	Actual Value	Remarks
8.9.1.6	Perform drilling of marked grounding strap I/F holes in side panel 3. For drilling remove SPIRE WU's from side panel. Use vacuum cleaner.			ESD precautions to be respected
8.9.1.7	Perform cleaning of side panel 3 with IPA and lint free rags			
8.9.1.8	Final mech. installation of SPIRE WU's on side panel 3: <ul style="list-style-type: none"> • DCU • FCU • DPU Screw down of SPIRE WU's fixation screws with defined torque Torque to be applied Marking of fixation screws after application of defined torque	M5 - 3.8 Nm ± 0.3 Nm M6 - 5.0 Nm ± 0.5 Nm		ESD precautions to be respected

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

8.10 Grounding of SPIRE Warm Units (WU's)

Step	Activity	Nominal Value	Actual Value	Remarks
8.10.1.1	Installation of grounding straps from SPIRE WU's to side panel 3: <ul style="list-style-type: none"> • DCU • FCU Screw down of SPIRE grounding straps fixation screws with defined torque Torque to be applied Marking of fixation screws after application of defined torque	M5 - 3.8 Nm ± 0.3 Nm		ESD precautions to be respected
8.10.1.2	Perform grounding verification measurement between SPIRE WU's housings and side panel 3 Documentation of measured values: <ul style="list-style-type: none"> • DCU • FCU • DPU Use bonding measurement device Metrawatt with Kelvin probes in four wire measurement technique and 1 amp measurement current	≤ 2.5 mOhm		ESD precautions to be respected

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

8.11 Installation of SPIRE Warm Units Interconnecting Harness

Step	Activity	Nominal Value	Actual Value	Remarks
8.11.1.1	Pre-installation and definition of routing of SPIRE WU's interconnecting harness onto side panel 3 Copy positions of cable tie anchors onto side panel 3			
8.11.1.2	Fixation of cable tie anchors on side panel 3 according marked positions of step before			
8.11.1.3	Final fixation of SPIRE interconnecting harness on side panel 3			
8.11.1.4	Make contact of SPIRE warm units interconnecting harness with WU's. To be performed by SPIRE instrument representative			ESD precautions to be respected

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

8.12 SPIRE WU's Bench Test

Step	Activity	Nominal Value	Actual Value	Remarks
8.12.1.1	General Remark: SPIRE stand alone test will be performed with instrument provided EGSE and procedure SPIRE-RAL-PRC-002422			Test can be performed with side panel away or side panel installed onto SVM simulator
8.12.1.2	If side panel 3 is not installed perform installation of side panel 3 onto SVM simulator. For movement use facility crane and standard hoisting slings. Screw down side panel 3 onto SVM simulator (-Z axis) <ul style="list-style-type: none"> • application of defined torque. Torque to be applied 	M8 - 15 Nm ± 0.5 Nm		

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

8.13 Integration of SIH Support Brackets to SVM Simulator Closure Panels

Step	Activity	Nominal Value	Actual Value	Remarks
8.13.1.1	<p>General Remark: This activity have to be performed by use of the following dedicated documents:</p> <ul style="list-style-type: none"> Herschel EQM Cryostat Harness SVM Internal SIH 2547-151430-300-01-0A 			
8.13.1.2	<p>Perform incoming inspection of SVM harness support brackets:</p> <ul style="list-style-type: none"> cleaning and cleanliness inspection of ext. surfaces visual inspection completeness of documentation (ADP) 			
8.13.1.3	<p>Integration of all harness support brackets to SVM closure panels Screw down of all SIH support bracket fixation screws with defined torque Torque to be applied Marking of fixation screws after application of defined torque</p>	M6 - 5.0 Nm ± 0.5 Nm		

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

8.14 Installation of SVM HIFI SIH from SVM Harness Brackets to HIFI Warm Units I/F's

Step	Activity	Nominal Value	Actual Value	Remarks
8.14.1.1	<p>General Remark: This activity have to be performed by use of the following documents:</p> <ul style="list-style-type: none"> Herschel PFM Cryostat harness SVM internal CCH & SIH HP-2-ASED-ID-0083-01-0A page 1-3 (use of EQM relevant information) 			
8.14.1.2	<p>Perform incoming inspection of SVM HIFI SIH:</p> <ul style="list-style-type: none"> cleaning and cleanliness inspection visual inspection <p>completeness of documentation (ADP)</p>			
8.14.1.3	Installation/Routing of HIFI SIH from SVM harness brackets to HIFI WU's I/F's			
8.14.1.4	Electrical verification of HIFI SIH and documentation of results			

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

8.15 Installation of External PACS SIH from SVM Brackets to PACS Warm Units I/F's

Step	Activity	Nominal Value	Actual Value	Remarks
	<p>General Remark: This activity have to be performed by use of the following documents:</p> <ul style="list-style-type: none"> Herschel PFM Cryostat harness SVM internal CCH & SIH HP-2-ASED-ID-0083-01-0A page 5 (use of EQM relevant information) 			
8.15.1.1	<p>Perform incoming inspection of SVM PACS SIH:</p> <ul style="list-style-type: none"> cleaning and cleanliness inspection visual inspection <p>completeness of documentation (ADP)</p>			
8.15.1.2	<p>Installation/Routing of PACS SIH from SVM harness brackets to HIFI WU's I/F's</p>			
8.15.1.3	<p>Electrical verification of PACS SIH and documentation of results</p>			

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

8.16 Installation of External SPIRE SIH from SVM Brackets to SPIRE Warm Units I/F's

Step	Activity	Nominal Value	Actual Value	Remarks
8.16.1.1	<p>General Remark: This activity have to be performed by use of the following documents:</p> <ul style="list-style-type: none"> Herschel PFM Cryostat harness SVM internal CCH & SIH HP-2-ASED-ID-0083-01-0A page 4 (use of EQM relevant information) 			
8.16.1.2	<p>Perform incoming inspection of SVM SPIRE SIH:</p> <ul style="list-style-type: none"> cleaning and cleanliness inspection visual inspection <p>completeness of documentation (ADP)</p>			
8.16.1.3	Installation/Routing of SPIRE SIH from SVM harness brackets to HIFI WU's I/F's			
8.16.1.4	Electrical verification of SPIRE SIH and documentation of results			

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

8.17 Instrument WU's Bus and Power cabling integration on SVM lower panels for HIFI, PACS and SPIRE

Step	Activity	Nominal Value	Actual Value	Remarks
8.17.1.1	<p>General Remark: This activity have to be performed by use of the following documents:</p> <ul style="list-style-type: none"> • HIFI 1 HP-NXH-DW-1024 page 1-3 • HIFI 2 HP-NXH-DW-1023 page 1-4 • PACS HP-NXH-DW-1021 page 1-4 • SPIRE HP-NXH-DW-1022 page 1-5 • H-P-2-ASPI-SP-0902 page 16 HIFI 1553-A-Bus Page19 HIFI 1553-B-Bus Page10 PACS 1553-A-Bus Page13 PACS 1553-B-Bus Page 22 SPIRE 1553-A-Bus Page 25 SPIRE 1553-B-Bus 			
8.17.1.2	<p>Mechanical integration of the following EGSE Connector brackets</p> <p>SPIRE panel: bracket DB04</p> <p>HIFI panel 1: bracket DB06</p> <p>HIFI panel 2: bracket DB05</p> <p>PACS panel: bracket DB31 and bracket DB32</p>			
8.17.1.3	Integration of SPIRE bus and power cabling			
8.17.1.4	Integration of HIFI bus and power cabling			
8.17.1.5	Integration of PACS bus and power cabling			

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

8.18 Instrument WU's electrical integration Procedure with IDAS

Step	Activity	Nominal Value	Actual Value	Remarks
8.18.1.1	<p>General Remark: This activity have to be performed by use of the following documents:</p> <ul style="list-style-type: none"> • HIFI WU electrical integration Procedure with IDAS HP-2-ASED-TP-0058 • SPIRE WU electrical integration Procedure with IDAS HP-2-ASED-TP-0055 • PACS WU electrical integration Procedure with IDAS HP-2-ASED-TP-0057 			
8.18.1.2	<p>Perform instrument WU's testing: HIFI WU's according HP-2-ASED-TP-0058 PACS WU's according HP-2-ASED-TP-0057 SPIRE WU's according HP-2-ASED-TP-0055</p>			
8.18.1.3	<p>After successful HIFI WU's electrical integration test make contact between HIFI WU's and EGSE</p>			
8.18.1.4	<p>After successful PACS WU's electrical integration test make contact between PACS WU's and EGSE</p>			
8.18.1.5	<p>After successful SPIRE WU's electrical integration test make contact between SPIRE WU's and EGSE</p>			

Date:		Test Conductor:
Sequence started at:	Completed at:	AIT QA:

END OF DOCUMENT

	Name	Dep./Comp.		Name	Dep./Comp.
x	Alberti von Mathias Dr.	AOE22	X	Wietbrock Walter	AET12
	Barlage Bernhard	AED11		Wöhler Hans	AOE22
x	Bayer Thomas	AOA52			
	Fehringer Alexander	AOE13			
	Geiger Hermann	AOA52			
	Gerner Willi	AED11			
	Grasi Andreas	OTN/AET52			
	Grasshoff Brigitte	AET12			
	Hauser Armin	AOE22			
	Hendry David	Terma Resid.	x	Alcatel	ASP
	Hinger Jürgen	AOE22	x	ESA/ESTEC	ESA
X	Hohn Rüdiger	AED65			
	Huber Johann	AOA52		Instruments:	
	Hund Walter	ASE442	x	MPE (PACS)	MPE
x	Idler Siegmund	AED432	x	RAL (SPIRE)	RAL
	Ivány von András	FAE22	x	SRON (HIFI)	SRON
	Jahn Gerd Dr.	AOE22			
	Kalde Clemens	APE3		Subcontractors:	
	Kameter Rudolf	OTN/AET52		Air Liquide, Space Department	AIR
	Kettner Bernhard	AET42		Air Liquide, Space Department	AIRS
	Knoblauch August	AET32		Air Liquide, Orbital System	AIRT
	Koelle Markus	AOA53		Alcatel Bell Space	ABSP
X	Kroeker Jürgen	AED65		Astrium Sub-Subsyst. & Equipment	ASSE
	Kunz Oliver Dr.	AOE22		Austrian Aerospace	AAE
x	Lamprecht Ernst	OTN/ASI21		Austrian Aerospace	AAEM
	Lang Jürgen	ASE442		APCO Technologies S. A.	APCO
	Langfermann Michael	AOA51		Bieri Engineering B. V.	BIER
x	Mack Paul	OTN/AET52		BOC Edwards	BOCE
	Müller Jörg	AOA52		Dutch Space Solar Arrays	DSSA
x	Pastorino Michel	ASPI Resid.		EADS CASA Espacio	CASA
x	Peltz Heinz-Willi	AOE13		EADS CASA Espacio	ECAS
	Pietroboni Karin	AED65		EADS Space Transportation	ASIP
	Platzer Wilhelm	AED22		Eurocopter	ECD
	Rebholz Reinhold	AOA51		HTS AG Zurich	HTSZ
	Reuß Friedhelm	AED62		Linde	LIND
X	Rühe Wolfgang	AED65		Patria New Technologies Oy	PANT
x	Runge Axel	OTN/AET52		Phoenix, Volkmarsen	PHOE
	Sachsse Bernd	AED21		Prototech AS	PROT
X	Schink Dietmar	AED44		QMC Instruments Ltd.	QMC
x	Schlosser Christian	OTN/AET52		Rembe, Brilon	REMB
	Schmidt Rudolf	FAE22		Rosemount Aerospace GmbH	ROSE
	Schweickert Gunn	AOE22		RYMSA, Radiación y Microondas S.A.	RYM
	Steininger Eric	AED44		SENER Ingeniería SA	SEN
x	Stritter Rene	AED11		Stöhr, Königsbrunn	STOE
	Tenhaeff Dieter	AOE22		Terma A/S, Herlev	TER
	Thörmer Klaus-Horst Dr.	OTN/AED65			
	Wagner Klaus	AOE22			